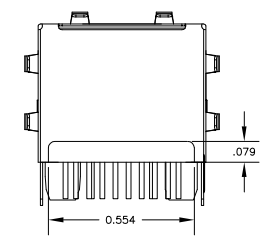
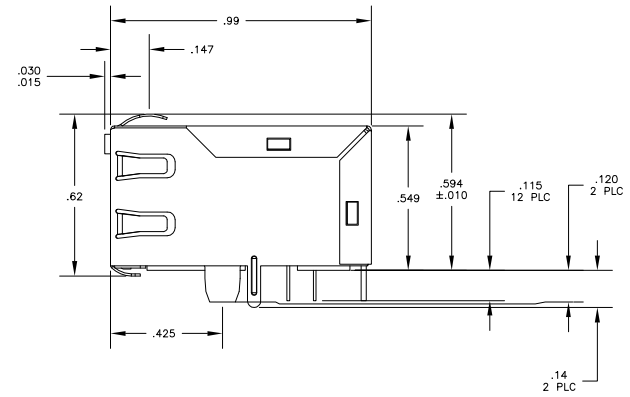
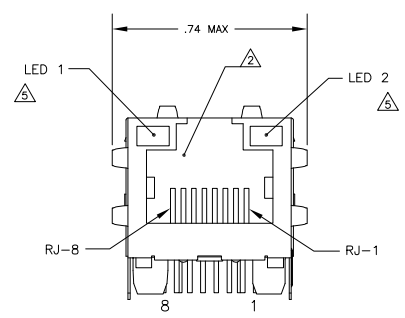
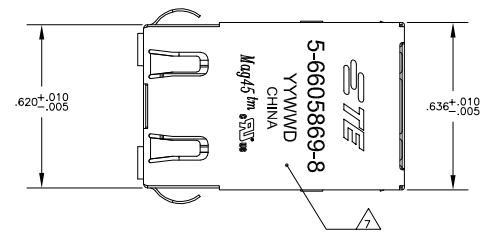


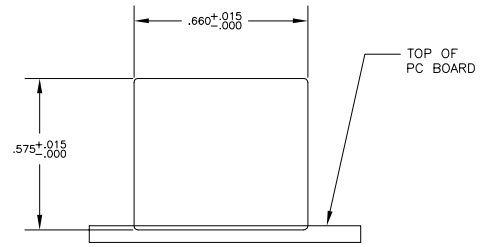
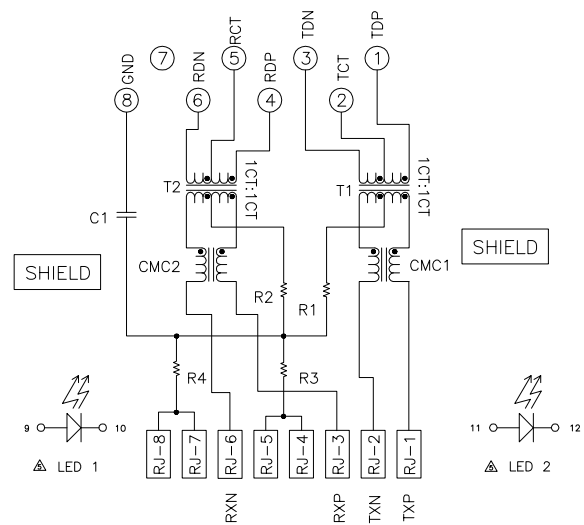
LOC	QST	REVISIONS	DATE	BY	APP
AA	00				
F		REV PER ECO-11-011343	12OCT2011	TY	KZ
G		ECO-11-013927	28OCT2011	EL	LR



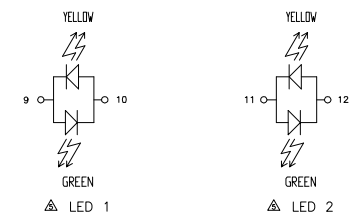
- 1 MATERIALS:
 HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 SHIELD - .008" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL; SOLDER TABS POST-DIPPED WITH SAC SOLDER.
 MOD JACK CONTACTS - .0157" x .018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" x .020" CARBON STEEL WIREFRAME LEADS PREPLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE; POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- 2 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- 3 MAGNETICS
 -APPLICATION: 10/100 BASE-T
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
- 5 LEADS WITHOUT BUILT-IN RESISTOR
 LEADS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20 mA
- 6 INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRIC, AND SUPPORT AUTO-MDI/MDIX.
- 7 TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
8. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

ELECTRICAL:

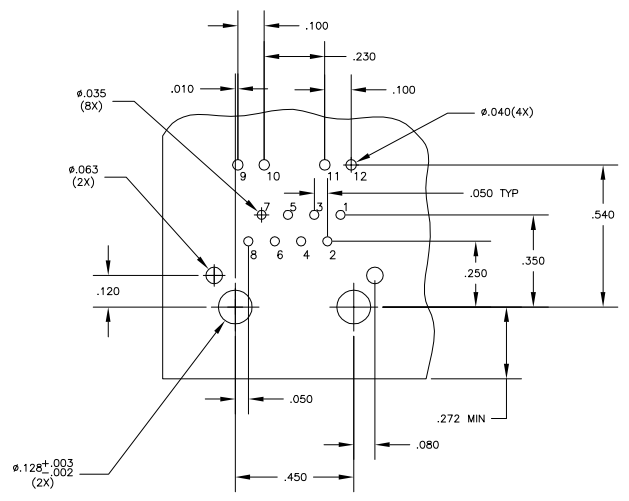
26P1 MAGNETIC SCHEMATIC:



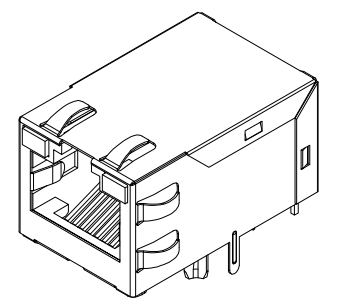
SUGGESTED PANEL CUTOUT



LED CONFIGURATION FOR 6605869-6 ONLY



SUGGESTED PC BOARD LAYOUT (Component Side)



GREEN	YELLOW	5-6605869-8
GREEN	GREEN	5-6605869-7
YELLOW	GREEN	6605869-9
GREEN/YELLOW	GREEN/YELLOW	6605869-6
LED 1	LED 2	PART NUMBER

C1=1000 pF, 2kV CAPACITOR
 R1-R4 =75 Ohms, 1/16 W RESISTORS

DIMENSIONS:		REV		DATE	
INCHES	NO DIMENSIONS SHOWN ARE UNLESS OTHERWISE SPECIFIED	1	2	31AUG2008	31AUG2008
0 P.A.C. ± .010	1 P.A.C. ± .005	2 P.A.C. ± .005	3 P.A.C. ± .005	4 P.A.C. ± .005	5 P.A.C. ± .005
MATERIAL	FINISH	WEIGHT	SCALE	SHEET	REV
TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY	TE CONNECTIVITY